CLAIMS

1. A method comprising:

disposing a low temperature solder on each of a plurality of interposer contacts on a reflow grid array (RGA) interposer; and

reflowing, at a low reflow temperature, the low temperature solder to form solid solder bumps, the solid solder bumps configured to be reflowed by the RGA interposer to solder a high temperature solder disposed on an electrical component to the low temperature solder of the solid bumps of the RGA interposer, wherein reflowing the low temperature solder includes heating an interposer heater trace disposed within the RGA interposer, and wherein the electrical component comprises electrical component solder bumps of the high temperature solder.

2. The method of claim 1, further including soldering the electrical component to the RGA interposer by heating the interposer heater trace to a high reflow temperature to reflow the low temperature solder of the solid solder bumps of the RGA interposer and the high temperature solder disposed on the electrical component.

3. The method of claim 2, wherein soldering the electrical component includes applying flux to the solid solder bumps of the RGA interposer.

4. The method of claim 3, wherein soldering the electrical component includes aligning the solid solder bumps of the RGA interposer with the electrical component solder bumps of the high temperature solder.

5. The method of claim 4, wherein aligning the solid solder bumps of the RGA interposer includes disposing an alignment fixture on the RGA interposer and disposing the electrical component within the alignment fixture.

6. The method of claim 2, wherein soldering the electrical component includes reflowing the electrical component solder bumps on the electrical component to form electrical contacts between the electrical component solder bumps and the solid solder bumps of the RGA interposer.

7. The method of claim 1, wherein disposing the low temperature solder on each of the plurality of interposer contacts includes disposing the low temperature solder in each of a

plurality of vacant spaces within an interposer contact mask, the plurality of vacant spaces corresponding to the plurality of interposer contacts.

8. An apparatus comprising:

a reflow grid array (RGA) interposer including a heater trace and a plurality of interposer contacts;

solid solder bumps of low temperature solder reflowed on each of the plurality of interposer contacts, wherein the solid solder bumps of low temperature solder are configured to be reflowed by the RGA interposer to solder a high temperature solder disposed on an electrical component to the low temperature solder of the solid bumps of the RGA interposer, wherein the electrical component comprises electrical component solder bumps of the high temperature solder.

9. An apparatus comprising:

a reflow grid array (RGA) interposer including a heater trace and a plurality of interposer contacts;

solid solder bumps of low temperature solder reflowed on each of the plurality of interposer contacts; and

an electrical component having electrical component bumps of high temperature solder wherein the electrical component bumps of high temperature solder are soldered to the solid bumps of low temperature solder of the RGA interposer, wherein the heater trace is configured to reflow the solid solder bumps of low temperature to solder the electrical component to the RGA interposer.

10. The apparatus of claim 9, further including an alignment fixture to align the electrical component with the RGA interposer.

11. An apparatus comprising:

a reflow grid array (RGA) interposer including a heater trace and a plurality of interposer contacts; and

an RGA interposer solder application device to facilitate application of a low temperature solder deposit to each of the plurality of interposer contacts, the heater trace configured to reflow the low temperature solder deposit to form solid solder bumps on each of the plurality of interposer contacts;

a flux layer applied across the low temperature solder deposits applied on the interposer contacts of the RGA interposer; and

a ball grid array (BGA) package comprising at least one high temperature solder sphere, wherein the at least one high temperature solder sphere is positioned over the low temperature solder deposit of the solid solder bumps of the RGA interposer, and

wherein the solid solder bumps are configured to be reflowed by the RGA interposer to solder the at least one high temperature solder sphere to the low temperature solder deposit of the solid solder bumps of the RGA interposer.

12. The apparatus of claim 11, wherein the RGA interposer solder application device includes an interposer contact mask, the interposer contact mask including a plurality of mask spaces corresponding to the plurality of interposer contacts.

13. The apparatus of claim 12, wherein the interposer contact mask includes a contact mask solder deposit within each of the plurality of mask spaces.

14. The apparatus of claim 13, wherein the RGA interposer solder application device includes a solder film, the solder film configured to dispose a solder film solder deposit on each of the plurality of interposer contacts.